

**What is claimed is:**

**1. A surface protective film for transparent conductive films protecting a surface of a side opposite to a conductive thin film or a surface on a side of a conductive thin film of the transparent conductive film, wherein an adhesive layer is formed on one side of a base material film, and a rate of thermal shrinkage after being heated at 150°C for 1 hour shows no more than 0.9% in both MD (machine direction) and TD (width direction).**

**2. The surface protective film for transparent conductive films according to Claim 1, wherein a treatment for removing a residual stress is performed to the base material film.**

**3. The surface protective film for transparent conductive films according to Claim 1, wherein the base material film is a film including polyethylene terephthalates and/or polyethylene naphthalates.**

**4. A transparent conductive film with surface protective film, wherein a conductive thin film is formed on one side of a base material film and a hard coat layer or an anti-glare layer is formed on the other surface side, and simultaneously an adhesive layer of the surface protective film for transparent conductive films according to Claims 1 through 3 is attached on a surface of the hard coat layer or the anti-glare layer, or the surface of conductive thin film.**

**5. A transparent conductive film with surface protective film wherein**  
**a conductive thin film is formed on one side of a base material film,**  
**and simultaneously an adhesive layer of the surface protective film**  
**for transparent conductive films according to Claims 1 through 3 is**  
**attached on the other surface side of the base material film or on a**  
**surface of the conductive thin film.**

**6. A method for manufacturing a surface protective film for**  
**transparent conductive films according to Claim 2 or 3, wherein**  
**after an adhesive is applied to one side of a base material film, a**  
**drawing tension of no more than 80 N per width of 1 m of the base**  
**material film is applied under conditions of a temperature of 100**  
**through 150°C, and a residence time of 20 through 120 seconds,**  
**and thereby a treatment for removing a residual stress and**  
**simultaneous drying of the adhesive are performed.**